**TEST PLAN AND OUTPUT:**

**LOW LEVEL TEST PLAN:**

|  |  |  |
| --- | --- | --- |
| **S.NO** | **DESCRIPTION** | **STATUS** |
| **LL01** | **Circuit design** | **implemented** |
| **LL02** | **Components assemble** | **implemented** |
| **LL03** | **Simulation** | **implemented** |
| **LL04** | **Code analysis** | **implemented** |

**HIGH LEVEL TEST PLAN:**

|  |  |  |
| --- | --- | --- |
| **S.NO** | **DESCRIPTION** | **STATUS** |
| **HL01** | **Temperature sensor** | **>100degree-danger** |
| **HL02** | **Heart beat sensor** | **Pulse rate=seconds-Good** |
| **HL03** | **Buzzer** | **Sound display-implemented** |
| **HL04** | **LCD Display** | **Display-implemented** |
| **HL05** | **GSM** | **Output messages-implemented.** |